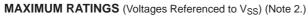
Dual J-K Flip-Flop

The MC14027B dual J–K flip–flop has independent J, K, Clock (C), Set (S) and Reset (R) inputs for each flip–flop. These devices may be used in control, register, or toggle functions.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Swing Independent of Fanout
- Logic Edge—Clocked Flip—Flop Design —
 Logic state is retained indefinitely with clock level either high or low; information is transferred to the output only on the positive—going edge of the clock pulse
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4027B



Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 3.)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \ or \ V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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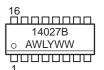
MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648

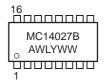








SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

WL or L = Wafer Lot YY or Y = Year WW or W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC14027BCP	PDIP-16	2000/Box
MC14027BD	SOIC-16	2400/Box
MC14027BDR2	SOIC-16	2500/Tape & Reel
MC14027BF	SOEIAJ-16	See Note 1.
MC14027BFEL	SOEIAJ-16	See Note 1.

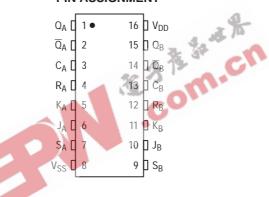
 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

TRUTH TABLE

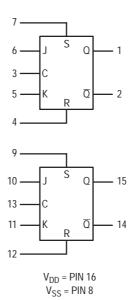
		Outp	uts*				
Cţ	J	K	S	R	Q _n ‡	Q _{n+1}	Q _{n+1}
	1	Х	0	0	0	1	0
	Х	0	0	0	1	1	0
	0	Х	0	0	0	0	1
	Х	1	0	0	1	0	1
	1	1	0	0	Qo	Qo	Qo
~	Х	Х	0	0	Х	Q _n	$\overline{Q_n}$
Х	Х	Х	1	0	Х	1	0
Х	Х	Х	0	1	Х	0	1
Х	Х	Х	1	1	Х	1	1

No Change

PIN ASSIGNMENT



BLOCK DIAGRAM



X = Don't Care

^{† =} Level Change

^{‡ =} Present State

^{* =} Next State

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V _{DD}	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ ^(4.)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15	_ _ _	1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	I _{ОН}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	l _{OL}	5.0 10 15	0.64 1.6 4.2	-	0.51 1.3 3.4	0.88 2.25 8.8	_	0.36 0.9 2.4	_ _ _	mAdc
Input Current		I _{in}	15		± 0.1	_ _	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}			-	8	5.0	7.5	_	ı	pF
Quiescent Current (Per Package)		IDD	5.0 10 15		1.0 2.0 4.0	_ _ _	0.002 0.004 0.006	1.0 2.0 4.0	_ _ _	30 60 120	μAdc
Total Supply Current ^{(5.) (6} (Dynamic plus Quiesc Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	l _T	5.0 10 15			$I_{T} = (1$).8 μΑ/kHz) f l .6 μΑ/kHz) f 2.4 μΑ/kHz) f	+ I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

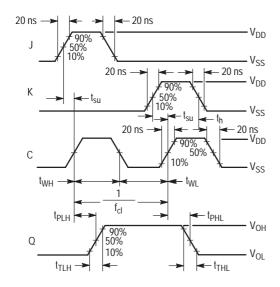
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.002.

SWITCHING CHARACTERISTICS (7.) (C $_L$ = 50 pF, T_A = 25 $^{\circ}$ C)

Characteristic	Symbol	V _{DD}	Min	Typ ^(8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns} \\ t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\ t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\ \end{cases}$	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Times** Clock to Q, Q t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 90 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 25 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	175 75 50	350 150 100	ns
Set to Q, Q t_{PLH} , t_{PHL} = (1.7 ns/pF) C_L + 90 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 42 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 25 ns		5.0 10 15	_ _ _	175 75 50	350 150 100	
Reset to Q, Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 265 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 67 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 50 \text{ ns}$		5.0 10 15	_ _ _	350 100 75	450 200 150	
Setup Times	t _{su}	5.0 10 15	140 50 35	70 25 17	_ _ _	ns
Hold Times	t _h	5.0 10 15	140 50 35	70 25 17	_ _ _	ns
Clock Pulse Width	t _{WH} , t _{WL}	5.0 10 15	330 110 75	165 55 38	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	_ _ _	3.0 9.0 13	1.5 4.5 6.5	MHz
Clock Pulse Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15		_ _ _	15 5.0 4.0	μs
Removal Times Set	t _{rem}	5 10 15	90 45 35	10 5 3	_ _ _	ns
Reset		5 10 15	50 25 20	- 30 - 15 - 10	_ _ _	
Set and Reset Pulse Width	t _{WH}	5.0 10 15	250 100 70	125 50 35	_ _ _	ns

^{7.} The formulas given are for the typical characteristics only at 25°C.
8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



Inputs R and S low. For the measurement of t_{WH} , l/f_{cl} , and P_D the Inputs J and K are kept high.

Figure 1. Dynamic Signal Waveforms (J, K, Clock, and Output)

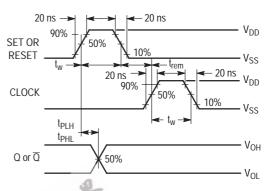
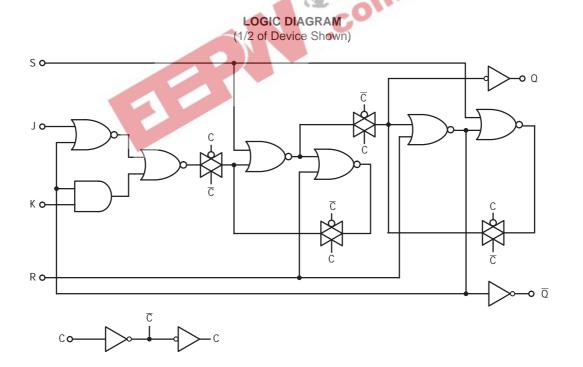
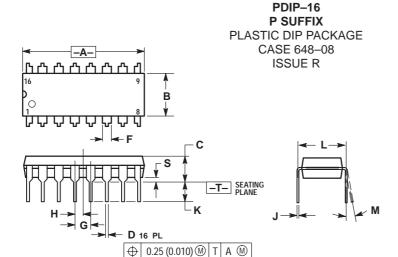


Figure 2. Dynamic Signal Waveforms (Set, Reset, Clock, and Output)



PACKAGE DIMENSIONS

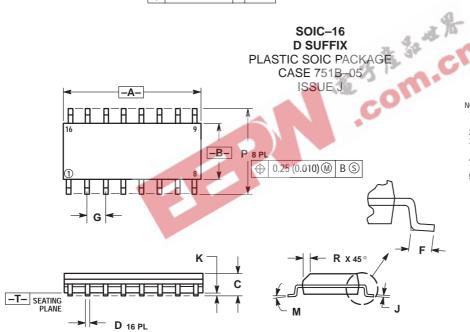


NOTES:

- NOTES:
 1 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN
 FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54 BSC	
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0°	10 °
S	0.020	0.040	0.51	1.01





⊕ 0.25 (0.010) M T B S A S

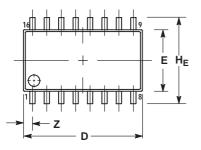
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

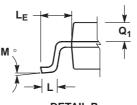
- PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

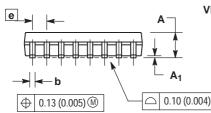
MILLIN	IETERS	INC	HES
MIN	MAX	MIN	MAX
9.80	10.00	0.386	0.393
3.80	4.00	0.150	0.157
1.35	1.75	0.054	0.068
0.35	0.49	0.014	0.019
0.40	1.25	0.016	0.049
1.27	BSC	0.050 BSC	
0.19	0.25	0.008	0.009
0.10	0.25	0.004	0.009
0°	7°	0°	7°
5.80	6.20	0.229	0.244
0.25	0.50	0.010	0.019
	MIN 9.80 3.80 1.35 0.35 0.40 1.27 0.19 0.10 0° 5.80	9.80 10.00 3.80 4.00 1.35 1.75 0.35 0.49 0.40 1.25 1.27 BSC 0.19 0.25 0° 7° 5.80 6.20	MIN MAX MIN 9.80 10.00 0.386 3.80 4.00 0.150 1.35 1.75 0.054 0.35 0.49 0.014 0.40 1.25 0.016 1.27 BSC 0.05(0.05(0.19 0.25 0.008 0.10 0.25 0.004 0° 7° 0° 5.80 6.20 0.229

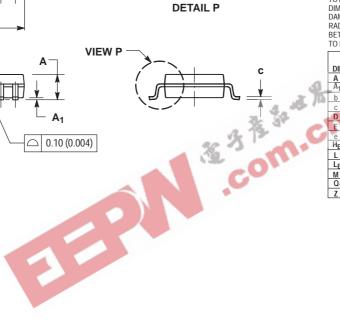
PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 ISSUE O









NOTES:

- JIES:

 1. DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS DAND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE
- MOLD FLASH OR PROTRUSIONS AND ARE
 MEASURED AT THE PARTING LINE. MOLD FLASH
 OR PROTRUSIONS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003) DAMIDAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMIDAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
Α ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		0.78		0.031



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Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-8549

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